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RESPONSE UNDER 37 C.F.R. § 1.116  
EXPEDITED PROCEDURE  
EXAMINING GROUP 2800

#10/1  
OKAY  
FEB 25 2003  
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TECHNOLOGY CENTER 2800

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

First Named  
Inventor : Ramesh Sundaram et al.

Appln. No.: 10/015,045

Filed : December 11, 2001

For : GLIDE HEADS AND METHODS FOR  
MAKING GLIDE HEADS

Docket No.: S01.12-0881

Group Art Unit 2856

Examiner: Thomas  
Noland

AMENDMENT AFTER FINAL

Commissioner for Patents  
BOX AF  
Washington, D.C. 20231

I HEREBY CERTIFY THAT THIS PAPER IS BEING  
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14 DAY OF February 2003  
Deutsche ZKvare  
PATENT ATTORNEY

Sir:

This is in response to the Office Action mailed on December 23, 2002. Please amend the above-identified application as follows:

IN THE CLAIMS

Please cancel claims 1-10.

Please amend claims 11, 13, 15-19, 23 and 25 as follows:

C1  
11. (Thrice Amended) A wafer including a glide head array including a plurality of rows and a plurality of columns of glide portions having air bearing surfaces formed on a surface of the wafer and an array of glide transducers on the wafer to form a plurality of glide heads.

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C2  
13. (Twice Amended) The wafer of claim 11 wherein said surface of the wafer has a flatness less than about 3  $\mu$ m.

C3  
15. (Twice Amended) The wafer of claim 11 wherein the surface of